IPC ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfg Information					
Supplier	r Information														
Company	name*	Company unique ID				Unique ID Authority					Response Date*				
onsemi												2023-06-08			
Contact N	ame	Title - Contact				Phone - Contact*				Email - Contact*					
Product-I	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorize	d Representative*	Title - Representative				Phone - Representative*				Email - Representative*					
Product-I	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Da	ate Version Manufacturing Site		ring Site	Weight*		UOM	Unit Type	
		LV5696P-E Car		Car Audio Power Supply		2023-06-08		]	РНМ		2	800.0	mg	Each	
Manufa	cturing Proccess Informat	tion													,
	Terminal Plating / Grid Array Material T		Cerminal Base Alloy J-STD-02		-STD-020 MSI	_ Rating	Peak Process Body Temperat		ure Max Time at Peak Temper		Temperatu	re Num	ber of Reflow Cyc	eles	
contains Bi		CU Alloy NA			0 C		30 seco		secono	ls 3					
Comments	<u> </u>														
or more	information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	8.22	mg	Supplier	Silicon (Si)	7440-21-3		8.1896	mg
			Supplier	Polyimide	Proprietary Data		0.0304	mg
Die Attach	2.39	mg	Supplier	Silver (Ag)	7440-22-4		0.0717	mg
			A	Lead (Pb)	7439-92-1	7a	2.2466	mg
			Supplier	Tin (Sn)	7440-31-5		0.0478	mg
			Supplier	Copper (Cu)	7440-50-8		0.0239	mg
Lead Frame	2002.18	mg	Supplier	Silver (Ag)	7440-22-4		2.0022	mg
			Supplier	Iron (Fe)	7439-89-6		1.802	mg
			Supplier	Copper (Cu)	7440-50-8		1998.1758	mg
			Supplier	Phosphorus (P)	7723-14-0		0.2001	mg
Mold Compound-Black	752.88	mg		Brominated epoxy resin	proprietary data		15.0576	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		1.5058	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		23.3393	mg
			Supplier	Carbon Black (C)	1333-86-4		2.2586	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		558.637	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		150.576	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.5058	mg
Plating	33.15	mg	В	Bismuth (Bi)	7440-69-9		0.1989	mg
			Supplier	Tin (Sn)	7440-31-5		32.9511	mg
Wire Bond - Au	1.18	mg	Supplier	Gold (Au)	7440-57-5		1.18	mg